

SOT506-1

plastic low profile quad flat package; 176 leads; body 24 x 24 x 1.4 mm

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	LQFP176
Package type industry code	LQFP176
Package style descriptive code	LQFP (low profile quad flat package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	136E25
JEDEC package outline code	MS-026
Mounting method type	S (surface mount)
Issue date	20-2-2003

Table 1. Package summary

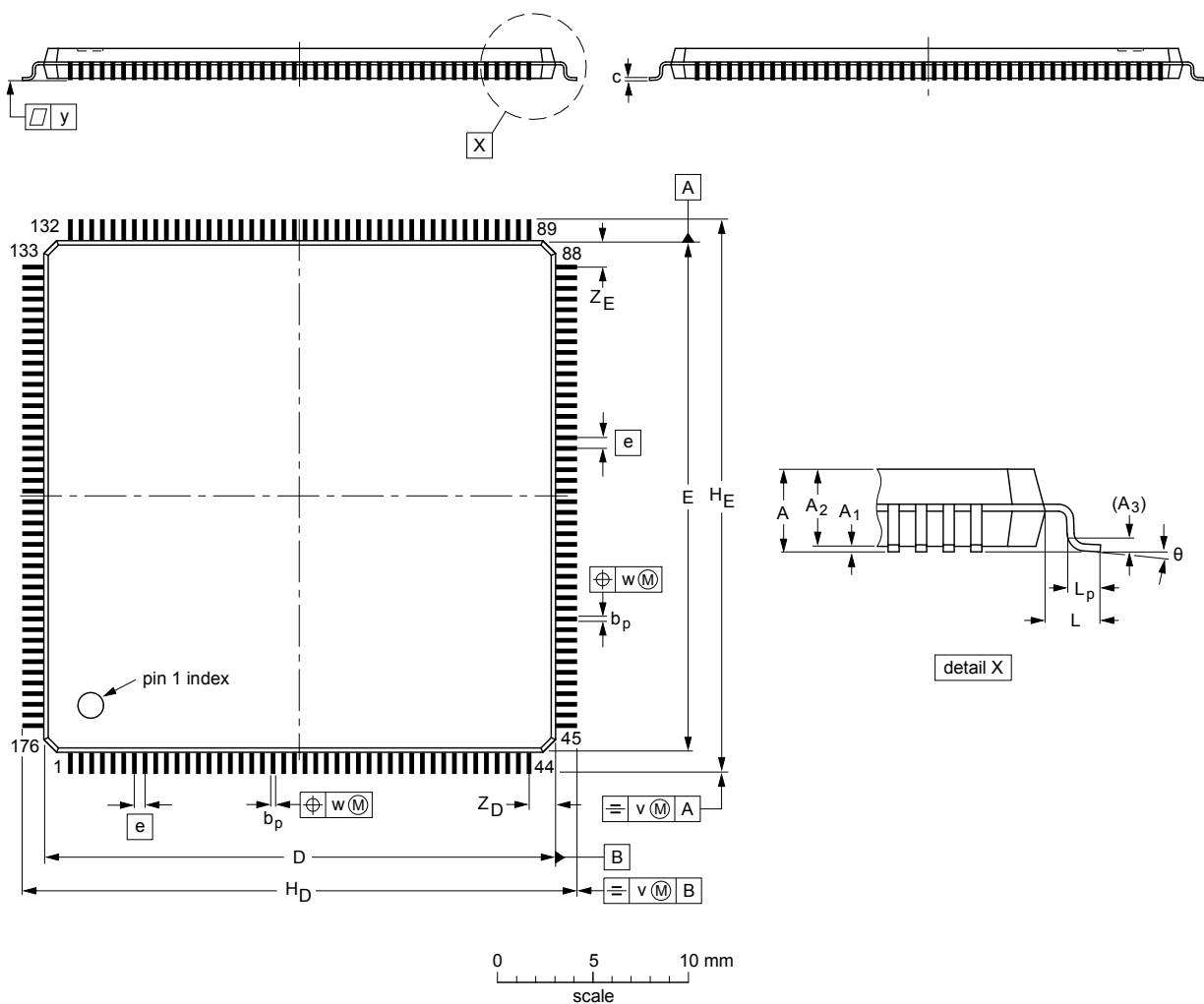
Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		23.9	-	24	24.1	mm
E	package width		23.9	-	24	24.1	mm
A	seated height		[tbd]	-	1.6	1.6	mm
A ₂	package height		1.35	-	1.4	1.45	mm
n ₂	actual quantity of termination		-	-	176	-	



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2. Package outline

LQFP176: plastic low profile quad flat package; 176 leads; body 24 x 24 x 1.4 mm SOT506-1



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽¹⁾	e	H _D	H _E	L	L _p	v	w	y	Z _D	Z _E	θ
mm	1.6	0.15 0.05	1.45 1.35	0.25	0.27 0.17	0.20 0.09	24.1 23.9	24.1 23.9	0.5	26.15 25.85	26.15 25.85	1	0.75 0.45	0.12	0.08	0.08	1.43 1.08	1.43 1.08	7° 0°

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT506-1	136E25	MS-026				00-02-01 03-02-20

Fig. 1. Package outline LQFP176 (SOT506-1)

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3. Soldering

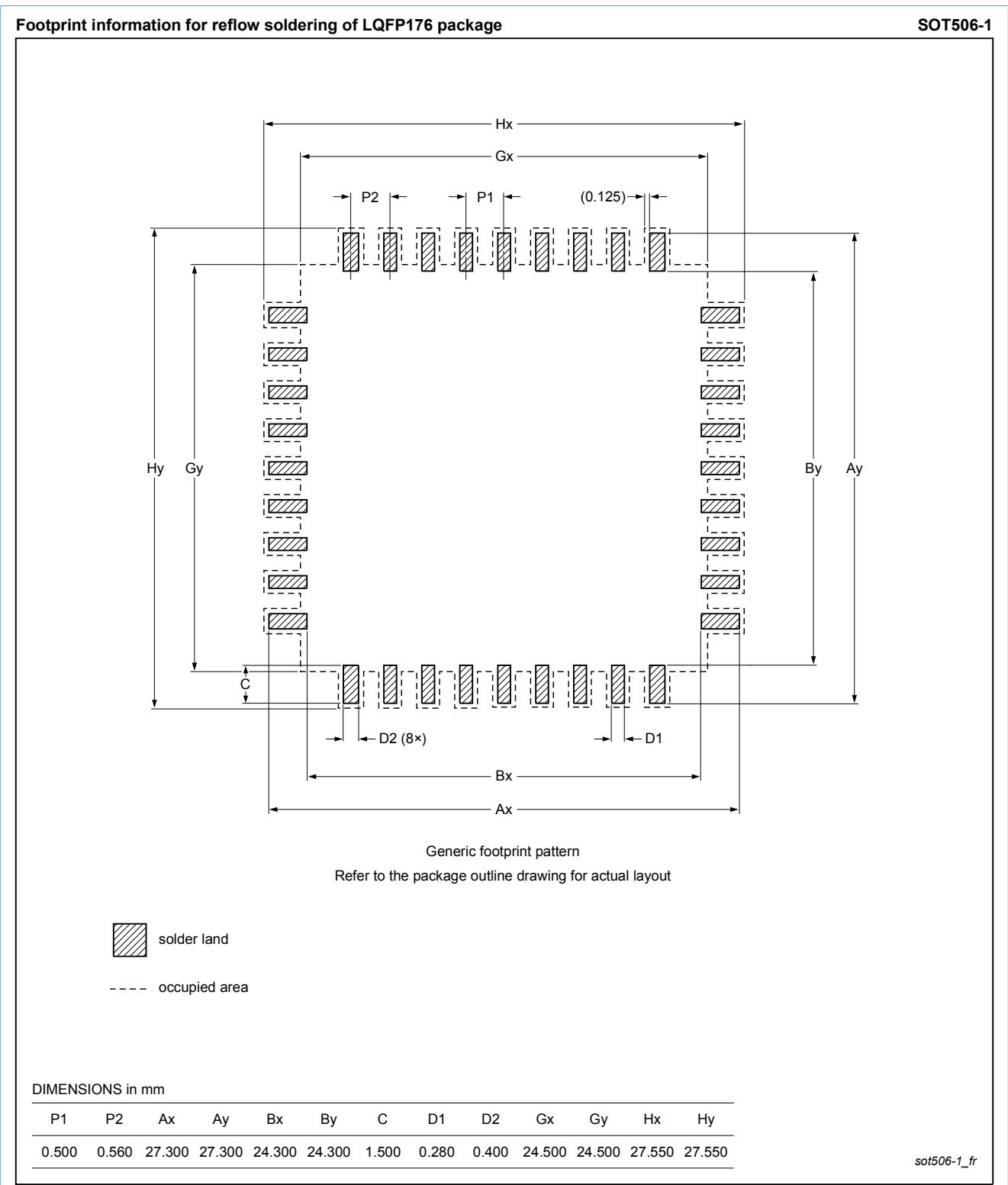


Fig. 2. Reflow soldering footprint for LQFP176 (SOT506-1)

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4. Legal information

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